**ECHATAH KINGDAVID EGHIEBADE**

**18/SCI01/025**

**CSC 202**

1. Greater ability of operating at extreme temperatures.
2. Very low cost because of simultaneous production of hundreds of similar circuits on a small semiconductor wafer. Owing to mass production of an IC costs as much as an individual transistor.
3. More reliable because of elimination of soldered joints and need for fewer interconnections.
4. Lower power consumption because of their smaller size.
5. Easy replacement as it is more economical to replace them than to repair them.
6. Increased operating speed because of absence of parasitic capacitance effect.
7. Close matching of components and temperature coefficients because of bulk production in batches.
8. Improved functional performance as more complex circuits can be fabricated for achieving better characteristics.